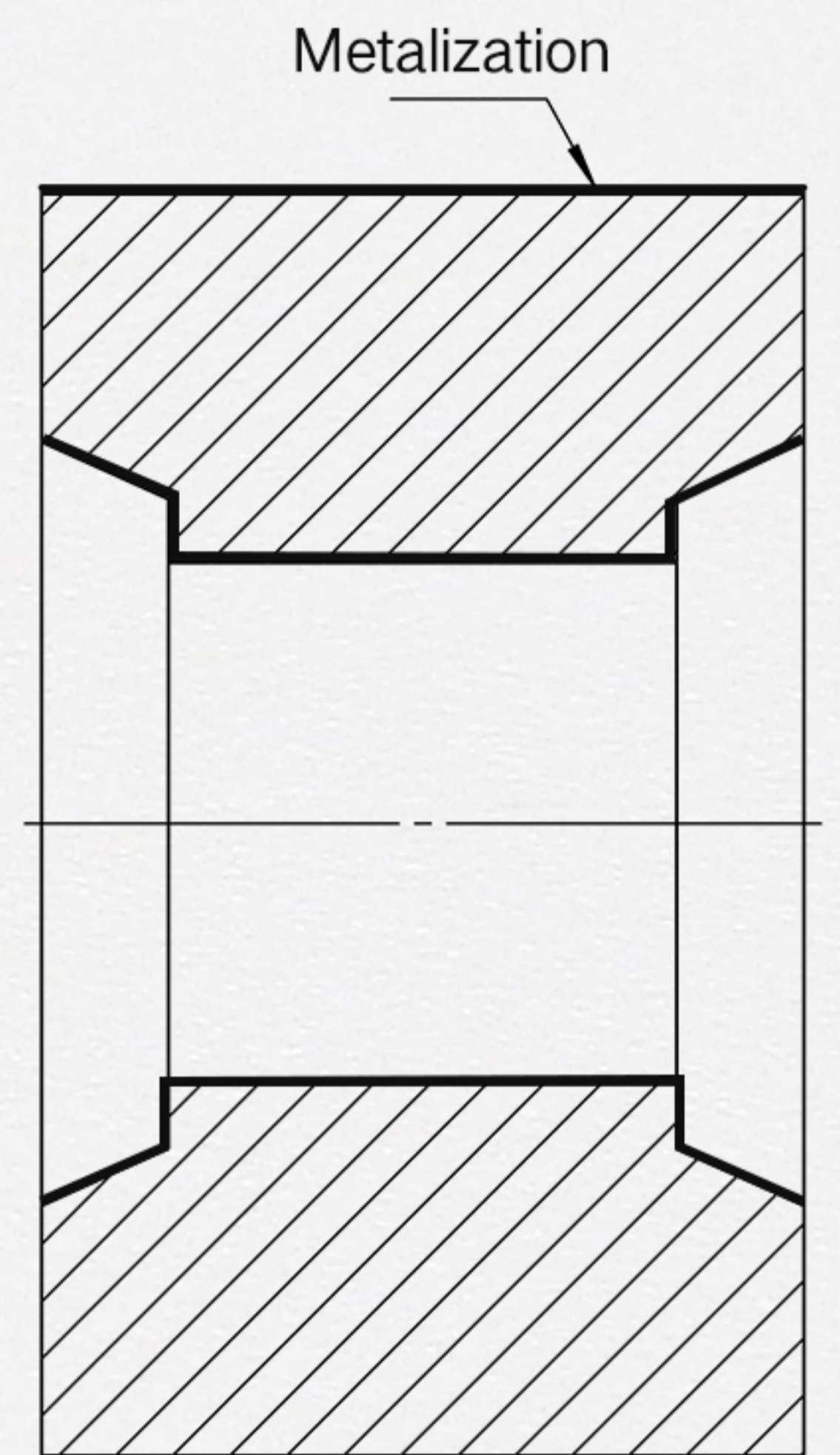


METALLIZED CERAMIC INSULATORS

Metallization Spec.

Molybdenum/Manganese (Mo/Mn) metallization: 9-30um

Ni plating thickness: 3-10um



Material Properties

No	Item	Unit	Value
1	Purity	%	≥95
2	Volume Density	g/cm ³	≥3.6
3	Water Absorption	%	0
4	Thermal Conductivity	W/m.k (25°C)	22.4
5	Coefficient of Thermal Expansion	(x10 ⁻⁶)/°C(25-1000°C)	8.2
6	Flexural Strength	MPa	340
7	Compressive Strength	MPa	2103
8	Tensile Strength	MPa	193
9	Hardness	Rockwell 45N	78
10	Withstand Voltage	K Vac/mm	8.3
11	Dielectric Constant	@1MHZ	9.1
12	Dielectric Loss Angle	@1MHZ	0.0004
13	Volume Resistivity (ohm-cm)	@25 °C	1x10 ⁻¹⁴
		@500 °C	4x10 ⁻⁹
		@1000 °C	5x10 ⁵

Features

1. The ceramic material is with even texture, each batch has stability quality and flexural strength.
2. Metal layer is dense, constant, smooth and good weldability.
3. Excellent electrical insulation, low dielectric constant, good abrasion, and corrosion resistance.
4. High tensile strength, good airtightness to meet the requirement of the high-frequency, high-power and safe electrical components.

Application

Semiconductor packaging, TO packaging, Fiber optic device shell, Laser Shell, Vacuum electronic devices, LED accessories etc.

